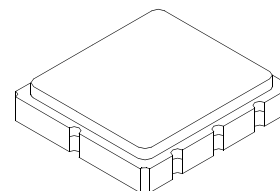


- *Designed for Broadband Receiver IF Applications*
- *Low Insertion Loss*
- *5.0 X 5.0 mm Surface-mount Case*
- *Differential Input and Single-ended Output*
- *Complies with Directive 2002/95/EC (RoHS)*


SF2120C
**149.00 MHz
SAW Filter**

SM5050-8

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminal	3	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Min	Typ	Max	Units
Nominal Center Frequency	f_C		149.00		MHz
Insertion Loss			2.0	2.5	dB
2 dB Passband		148 to 150	147.65 to 150.35		MHz
Amplitude Ripple, 148 to 150 MHz, -27.5 to 72.5 °C			1.5	1.8	dB _{P-P}
Amplitude Ripple, 148 to 150 MHz, -40 to -27.5 °C, 72.5 to 85 °C			2.0	2.2	dB _{P-P}
Rejection, f_C -2.5 MHz		15	54		dB
Rejection, f_C +2.5 MHz		15	30		dB
Center Frequency Temperature Coefficient			-30		ppm/K
Operating Temperature		-40		85	°C
Case Style		SM5050-8 5 x 5 mm Nominal Footprint			
Lid Symbolization (Y=year, WW=week, S=shift)		635, YWWS			

Electrical Connections - Differential Operation

Connection	Terminals
Port 1 Differential Input	1, 2
Port 2 Output	5
Ground	All others
Dot indicates Pin 1	

Electrical Connections - Single End Operation

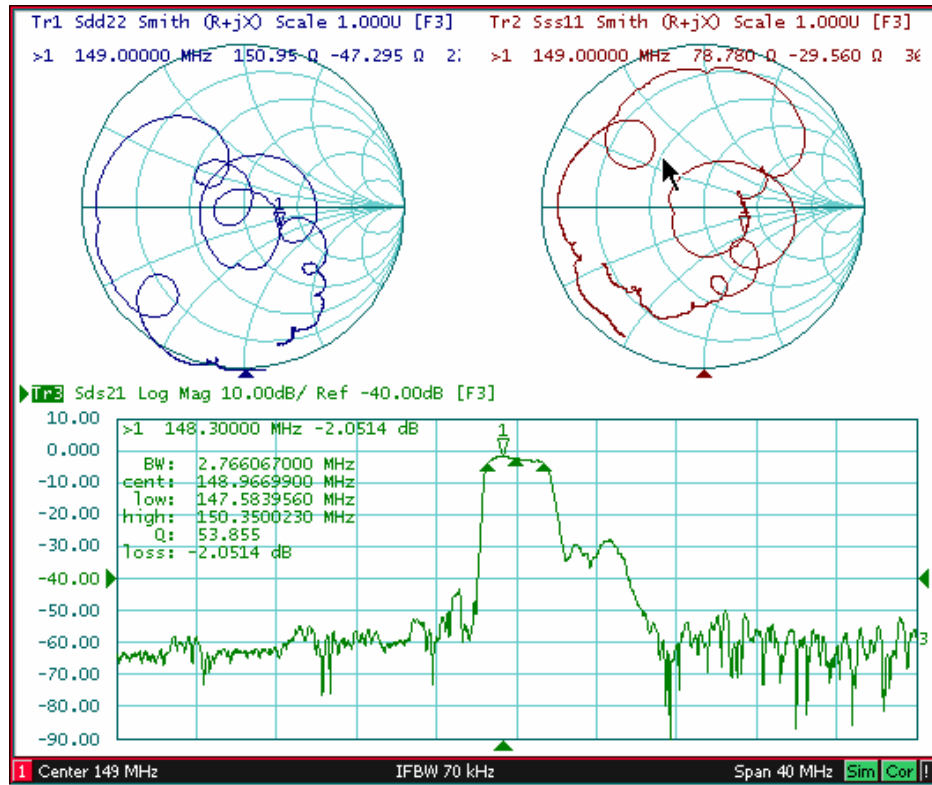
Connection	Terminals
Port 1 Input	1
Port 2 Output	5
Ground	All others
Dot indicates Pin 1	


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

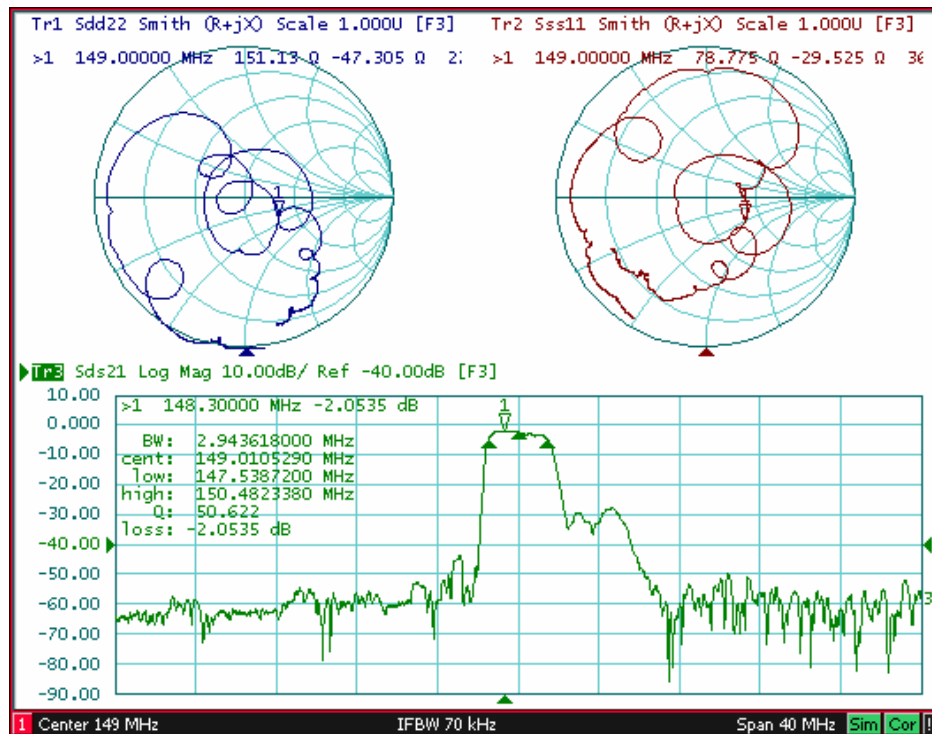
NOTES:

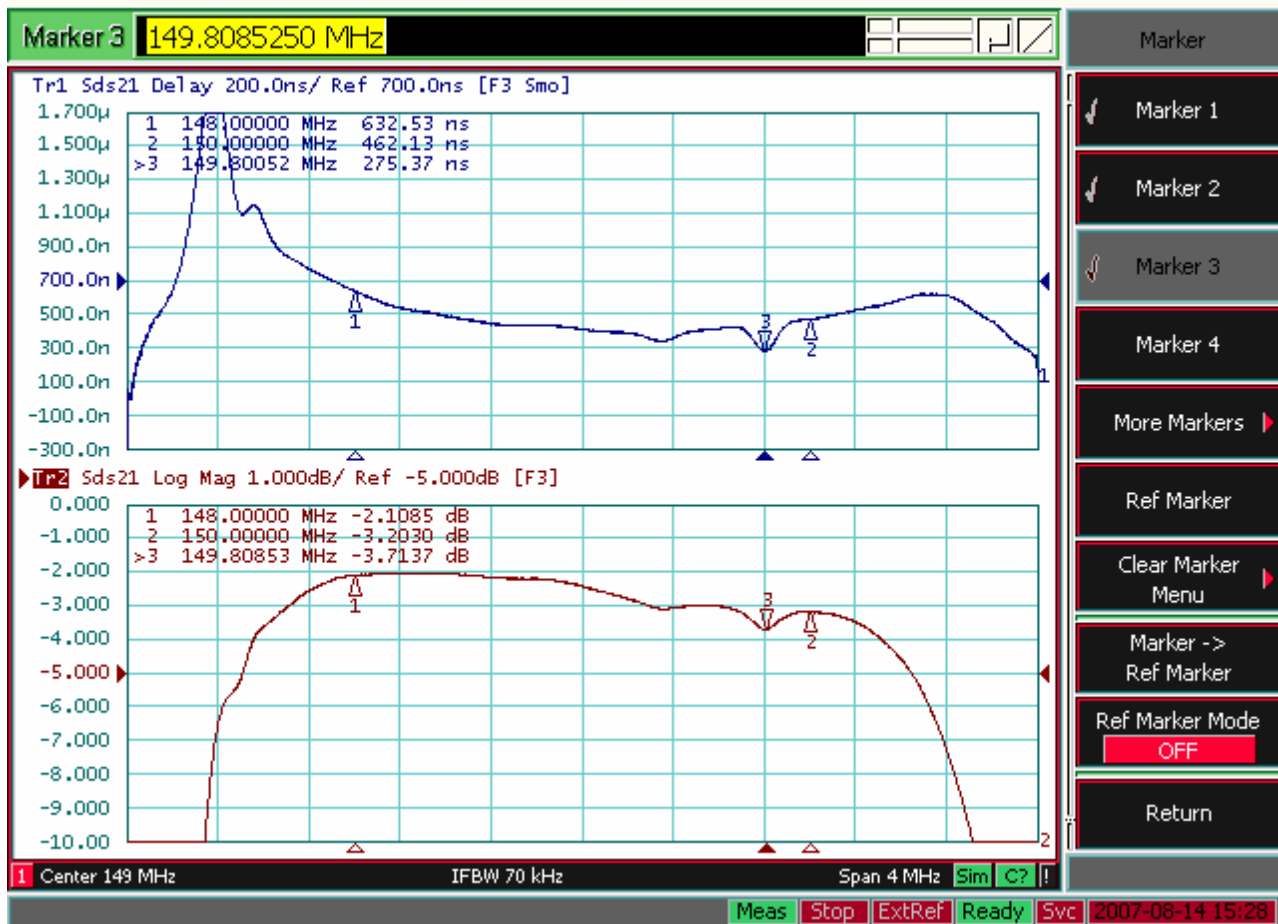
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

2 dB BW

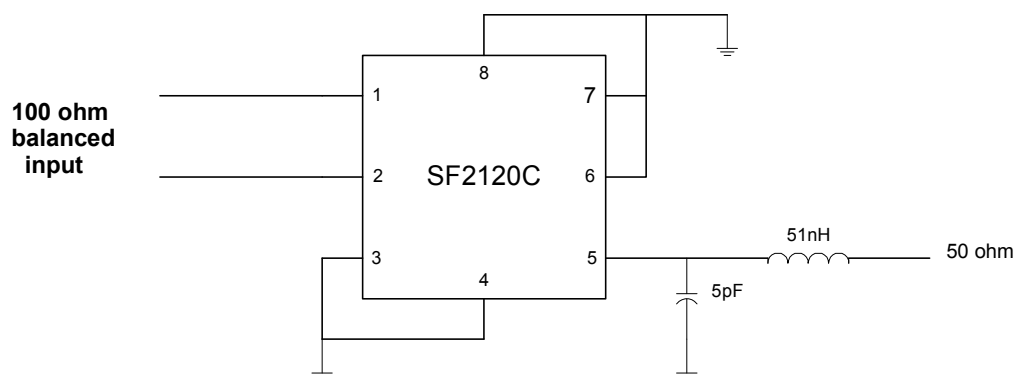


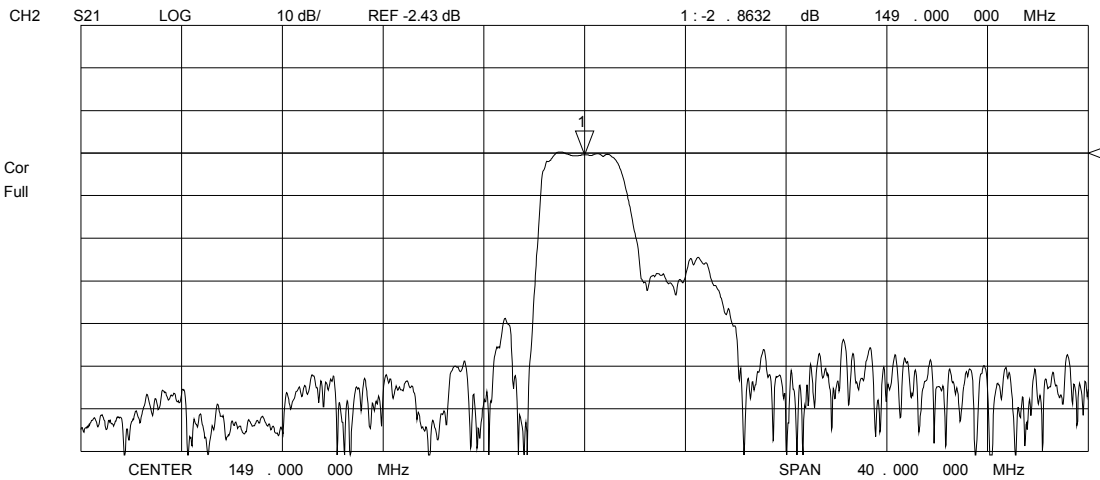
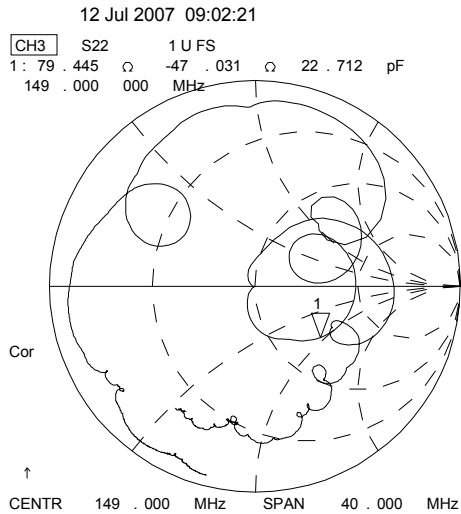
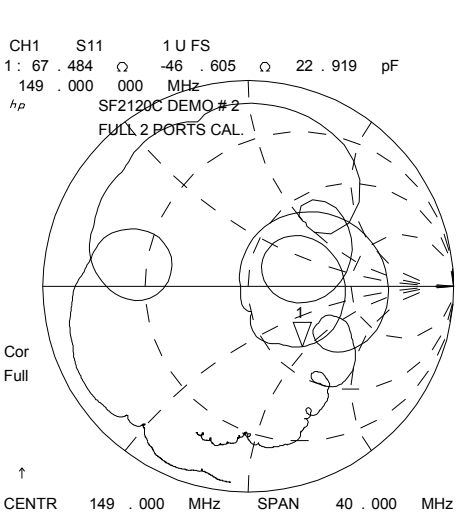
3 dB BW

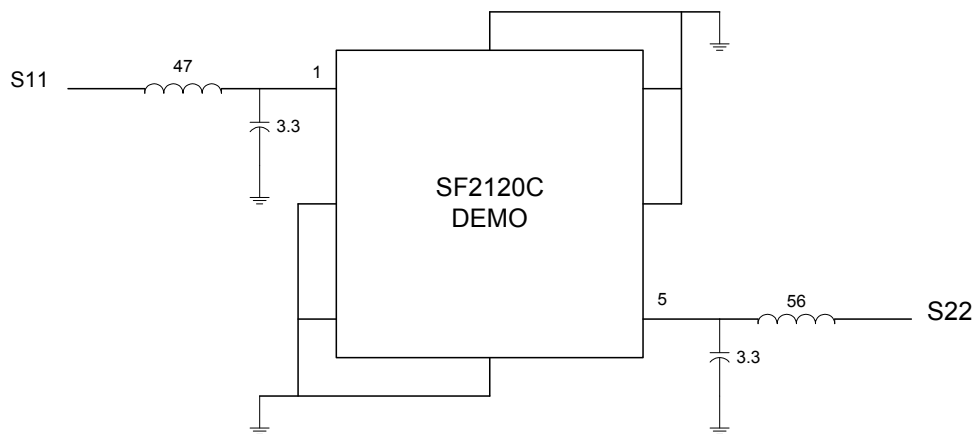
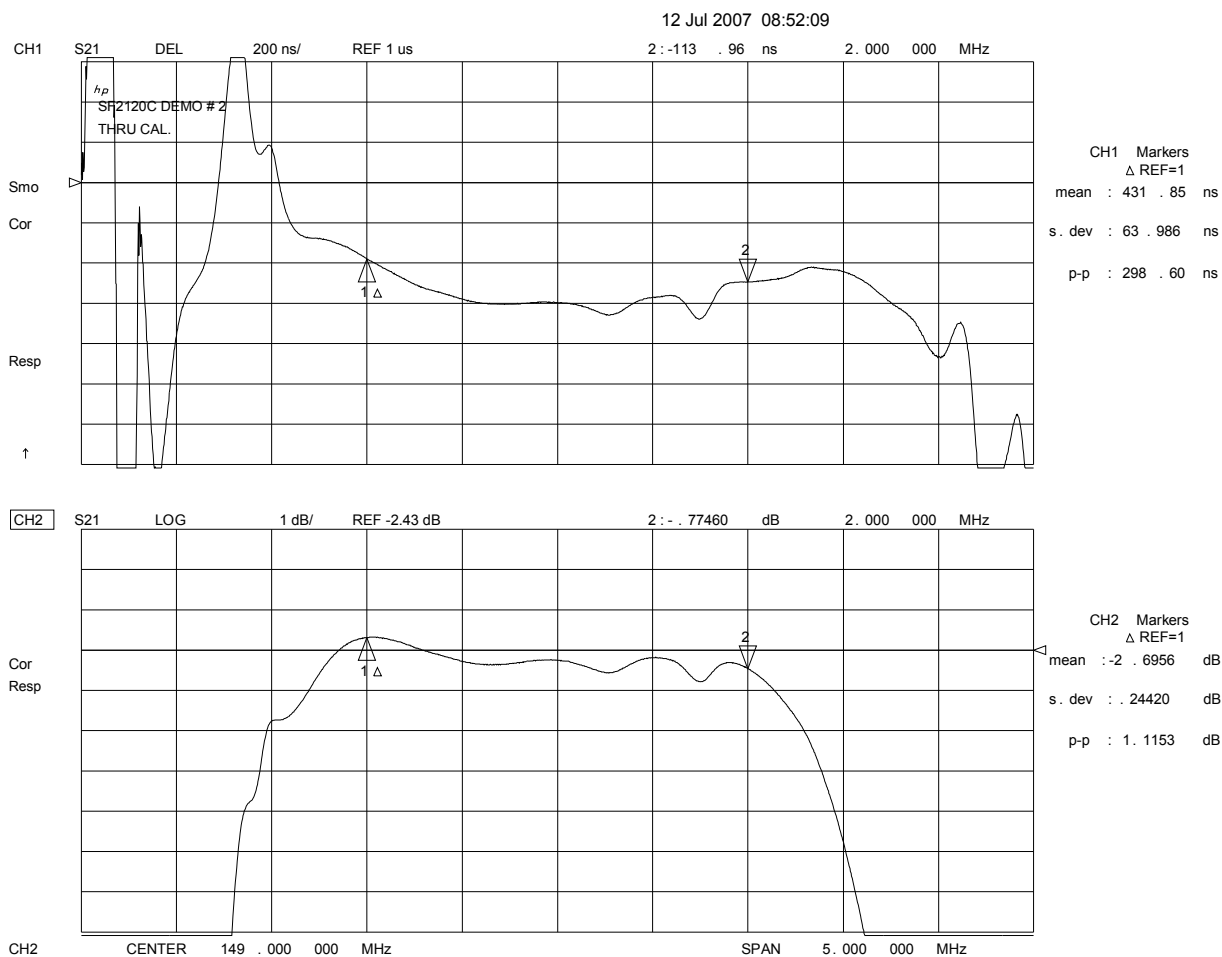




Electrical Connections







401-1624-001		
501-0782-470	0805, 47NH	L1
501-0782-560	0805, 56NH	L2
501-0621-033	0603, 3.3PF	C1, C2

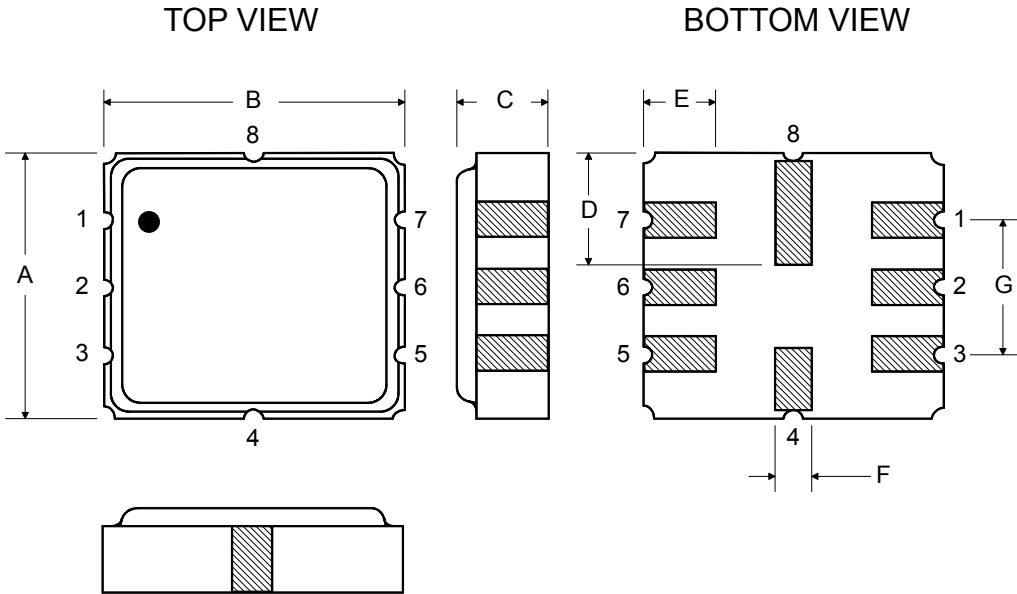
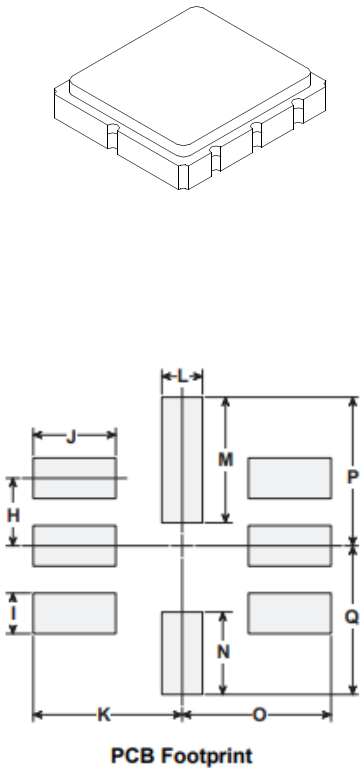
SM5050-8 Surface-Mount 8-Terminal Ceramic Case 5.0 X 5.0 mm Nominal Footprint

Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	4.80	5.00	5.20	0.189	0.197	0.205
B	4.80	5.00	5.20	0.189	0.197	0.205
C	1.30	1.50	1.70	0.050	0.060	0.067
D	1.98	2.08	2.18	0.078	0.082	0.086
E	1.07	1.17	1.27	0.042	0.046	0.050
F	0.50	0.64	0.70	0.020	0.025	0.028
G	2.39	2.54	2.69	0.094	0.100	0.106
H		1.27			0.050	
I		0.76			0.030	
J		1.55			0.061	
K		2.79			0.110	
L		0.76			0.030	
M		2.36			0.093	
N		1.55			0.061	
O		2.79			0.110	
P		2.79			0.110	
Q		2.79			0.110	

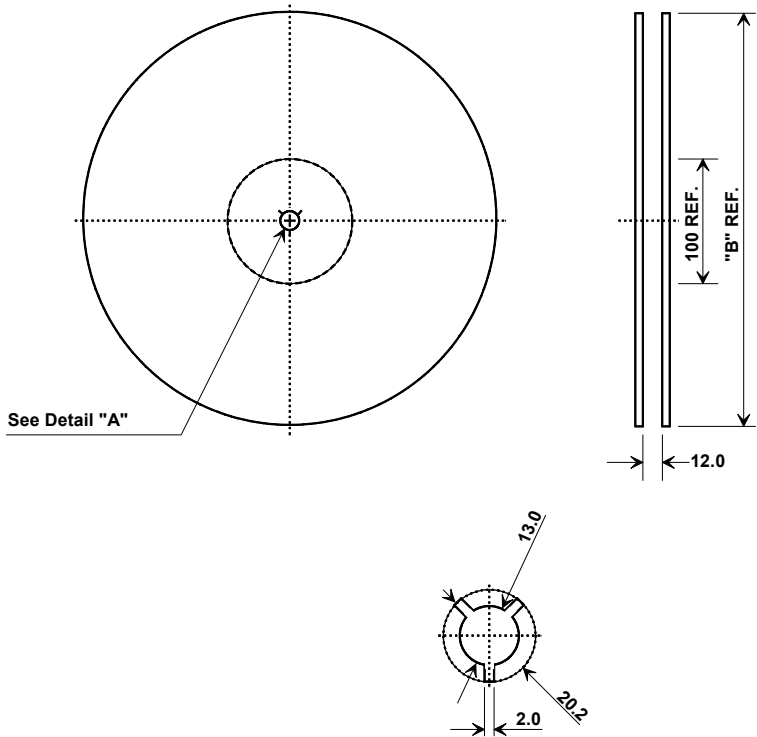
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	



Tape and Reel Specifications

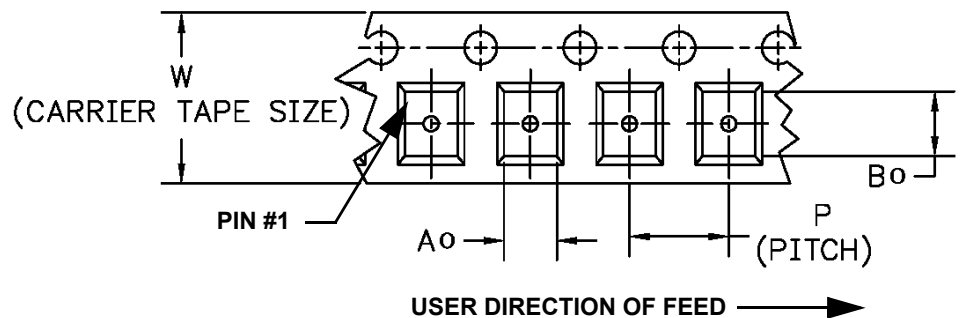
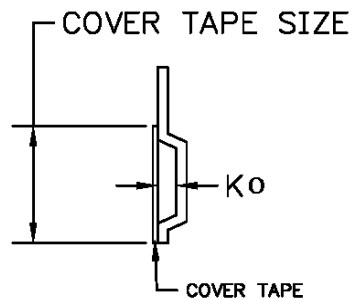
Tape and Reel Standard per ANSI/EIA-481



"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

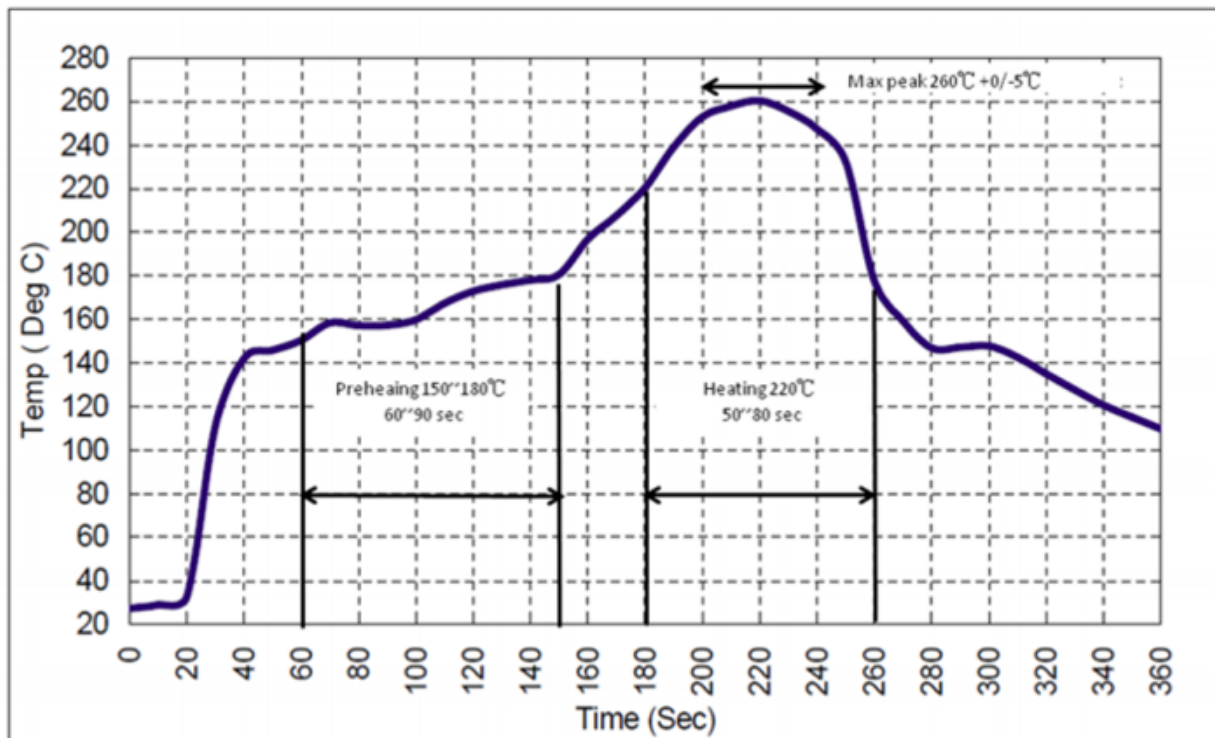
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.3 mm
Bo	5.3 mm
Ko	2.0 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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